

REMARKS

Reconsideration of the application in view of the above amendments and the following remarks is requested. Claims 2-11 are in this application. Claims 2, 5, and 7-11 have been amended. Claim 2 has been amended to be in independent format, and to broaden the claim. Claims 5 and 7-11 have also been amended to broaden the claims. Claim 1 has been cancelled.

The Examiner rejected claims 1-11 under 35 U.S.C. §102(b) as being anticipated by Lu (U.S. Patent No. 6,479,341 B1). For the reasons set forth below, applicant respectfully traverses this rejection.

Claim 2 recites:

“A method of processing a semiconductor material having a top surface and a bottom surface, the method comprising:

“forming a doped region in the top surface of the semiconductor material;

“forming a hole in the semiconductor material that extends through the semiconductor material . . . .”

In rejecting the claims, the Examiner pointed to the formation of doped region 8 shown in, for example, FIG. 2 of Lu as constituting the “forming a doped region” element of claim 2. Since the doped region required by claim 2 must be formed in the top surface of the semiconductor material, the semiconductor material must be read to be substrate 1 shown in FIG. 2 of Lu.

The Examiner argued that oxide layer 9 shown in FIG. 2 of Lu can be read to be the semiconductor material required by claim 2. However, as shown in FIG. 2 of Lu, doped region 8 is not formed in the top surface of oxide layer 9, but is instead formed in the top surface of substrate 1. As a result, the semiconductor material of claim 2 must be read to be substrate 1 shown in FIG. 2 of Lu.

In further rejecting the claims, the Examiner pointed to the formation of holes 10/11 shown in, for example, FIG. 2 of Lu as constituting the “forming a hole”

element of claim 2. However, as shown in FIG. 2 of Lu, it is not possible for holes 10/11 to extend through the semiconductor material (substrate 1) as required by claim 2 because holes 10/11 do not extend through any portion of the semiconductor material (substrate 1). As a result, the formation of holes 10/11 can not be read to be the "forming a hole" element of claim 2.

Thus, since the formation of holes 10/11 can not be read to be the required "forming a hole" element, claim 2 is not anticipated by the Lu reference. In addition, since claims 3-11 depend either directly or indirectly from claim 2, claims 3-11 are not anticipated by the Lu reference for the same reasons as claim 2.

Thus, for the foregoing reasons, it is submitted that all of the claims are in a condition for allowance. Therefore, the Examiner's early re-examination and reconsideration are requested.

Respectfully submitted,

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